



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	13-11-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G0B1VET6 STM32G0B1VET6TR	201L*467XXXZ	A	9991	13-11-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	680.94	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14	100	L bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2011*467XXXZ				6000000.0	1000000.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	13.900	mg	Supplier	die	Silicon (Si)	7440-21-3		13.563	mg	975755	19918				
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	1151	23				
				Supplier	metallization	Copper (Cu)	7440-50-8		0.143	mg	10288	210				
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.046	mg	3309	68				
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	144	3				
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	72	1				
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.036	mg	2590	53				
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.093	mg	6691	137				
				Leadframe (C7025 + Ag)	Copper & its alloys	190.000	mg	Supplier	Leadframe	Copper (Cu)	7440-50-8		174.610	mg	919000	256425
								Supplier	Leadframe	Nickel (Ni)	7440-02-0		5.890	mg	31000	8650
Supplier	Leadframe	Silicon (Si)	7440-21-3						2.280	mg	12000	3348				
Supplier	Leadframe	Magnesium (Mg)	7439-95-4						0.570	mg	3000	837				
Supplier	Leadframe	Silver (Ag)	7440-22-4						6.650	mg	35000	9766				
Supplier	Glue or tape	Silver (Ag)	7440-22-4						1.402	mg	779000	2059				
Glue Epoxy (EN-4900G)	Precious metals	1.800	mg	Supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.045	mg	25000	66				
				Supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.110	mg	61000	161				
				Supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.099	mg	55000	145				
				Supplier	Glue or tape	Butadiene copolymer	Proprietary		0.018	mg	10000	26				
				Supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.099	mg	55000	145				
				Supplier	Glue or tape	Peroxy Ketals	Proprietary		0.009	mg	5000	13				
				Supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.009	mg	5000	13				
				Supplier	Glue or tape	Methacrylate multialkoxy-substitutedalkyl ester	Proprietary		0.009	mg	5000	13				
Bonding wire (Cu)	Precious metals	1.000	mg	Supplier	Bonding wire	Copper (Cu)	7440-50-8		0.966	mg	965500	1418				
				Supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.031	mg	31000	46				
				Supplier	Bonding wire	Silver (Ag)	7440-22-4		0.004	mg	3500	5				
				Supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'	85954-11-6		18.134	mg	40000	26630				
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	453.340	mg	Supplier	Molding Compound	Epoxy resin	Proprietary		9.067	mg	20000	13315				
				Supplier	Molding Compound	Phenol Resin	Proprietary		34.001	mg	75000	49932				
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		321.645	mg	709500	472354				
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		68.001	mg	150000	99863				
				Supplier	Molding Compound	Carbon black	1333-86-4		2.493	mg	5500	3662				
External Plating (Sn)	M-011 Other inorganic materials	20.900	mg	Supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	30690				
				Supplier	Matte Sn	Impurities	-		0.002	mg	100	3				